

ABSTRACT OF THE DISCLOSURE

The present invention relates to a non-sensitizing epoxy composition including an uncured epoxy resin composition including a liquid epoxy resin and a non-sensitizing mercaptan composition capable of curing said epoxy resin when combined with said mercaptan composition
5 to form a substantially uniform mixture, wherein said epoxy resin has a molecular weight greater than about 700.

PHI\1024318.1